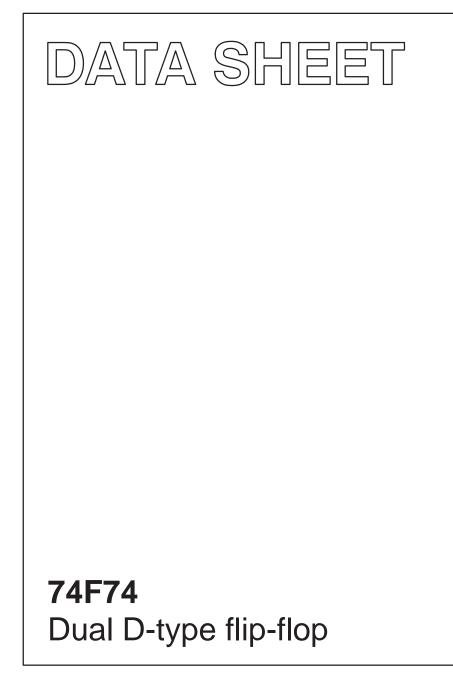
# INTEGRATED CIRCUITS



Product specification Supercedes data of 1990 Oct 23 IC15 Data Handbook 1996 Mar 12



Philips Semiconductors

74F74

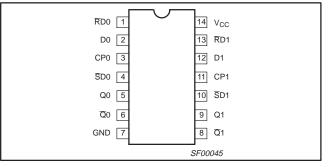
#### FEATURE

Industrial temperature range available (-40°C to +85°C)

#### DESCRIPTION

The 74F74 is a dual positive edge-triggered D-type flip-flop featuring individual data, clock, set, and reset inputs; also true and complementary outputs. Set (SD) and reset (RD) are asynchronous active low inputs and operate independently of the clock input. When set and reset are inactive (high), data at the D input is transferred to the Q and  $\overline{Q}$  outputs on the low-to-high transition of the clock. Data must be stable just one setup time prior to the low-to-high transition of the clock for predictable operation. Clock triggering occurs at a voltage level and is not directly related to the transition time of the positive-going pulse. Following the hold time interval, data at the D input may be changed without affecting the levels of the output.

## **PIN CONFIGURATION**



ТҮРЕ	TYPICAL f <sub>max</sub>	TYPICAL SUPPLY CURRENT (TOTAL)
74F74	125MHz	11.5mA

#### **ORDERING INFORMATION**

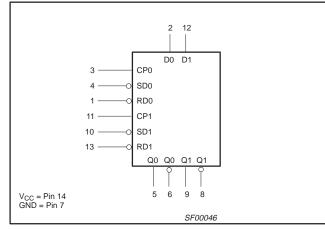
	ORDER	CODE	
DESCRIPTION	COMMERCIAL RANGE V <sub>CC</sub> = 5V ±10%, T <sub>amb</sub> = 0°C to +70°C	INDUSTRIAL RANGE V <sub>CC</sub> = 5V ±10%, T <sub>amb</sub> = −40°C to +85°C	PKG. DWG. #
14-pin plastic DIP	N74F74N	174F74N	SOT27-1
14-pin plastic SO	N74F74D	I74F74D	SOT108-1

## INPUT AND OUTPUT LOADING AND FAN OUT TABLE

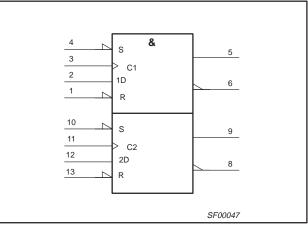
PINS	DESCRIPTION	74F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW		
D0, D1	Data inputs	1.0/1.0	20µA/0.6mA		
CP0, CP1	Clock inputs (active rising edge)	1.0/1.0	20µA/0.6mA		
SD0, SD1	Set inputs (active low)	1.0/3.0	20µA/1.8mA		
RD0, RD1	Reset inputs (active low)	1.0/3.0	20µA/1.8mA		
Q0, Q1, <u>Q</u> 0, <u>Q</u> 1	Data outputs	50/33	1.0mA/20mA		

NOTE: One (1.0) FAST unit load is defined as: 20µA in the high state and 0.6mA in the low state.

# LOGIC SYMBOL

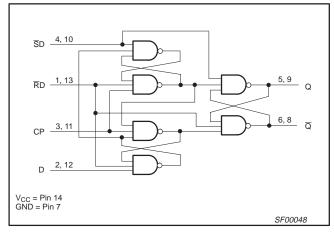


# **IEC/IEEE SYMBOL**



# 74F74

#### LOGIC DIAGRAM



#### **FUNCTION TABLE**

	INPU	JTS		OUT	PUTS	OPERATING
SD	RD	СР	D	Q	Q	MODE
L	Н	Х	Х	Н	L	Asynchronous set
Н	L	Х	Х	L	Н	Asynchronous reset
L	L	Х	Х	Н	Н	Undetermined*
Н	Н	Ŷ	h	Н	L	Load "1"
Н	Н	Ŷ	I	L	Н	Load "0"
Н	Н	1	Х	NC	NC	Hold

#### NOTES:

L

T

H = High voltage level

h = High voltage level one setup time prior to low-to-high clock transition

= Low voltage level

= Low voltage level one setup time prior to low-to-high clock transition

NC= No change from the previous setup

X ↑ = Don't care

- = Low-to-high clock transition
- Ŷ

 Not low-to-high clock transition
This setup is unstable and will change when either set or reset return to the high level.

### **ABSOLUTE MAXIMUM RATINGS**

(Operation beyond the limit set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free air temperature range.)

SYMBOL	PARAMETER		RATING	UNIT
V <sub>CC</sub>	Supply voltage		-0.5 to +7.0	V
V <sub>IN</sub>	Input voltage		-0.5 to +7.0	V
I <sub>IN</sub>	Input current		-30 to +5	mA
V <sub>OUT</sub>	Voltage applied to output in high output state		–0.5 to $V_{CC}$	V
IOUT	Current applied to output in low output state		40	mA
<b>-</b>		Commercial range	0 to +70	°C
T <sub>amb</sub>	Operating free air temperature range	-40 to +85	°C	
T <sub>stg</sub>	Storage temperature range	-65 to +150	°C	

# **RECOMMENDED OPERATING CONDITIONS**

SYMBOL	DADAMETED			LIMITS		UNIT
STMBOL	PARAMETER		MIN	NOM	MAX	UNIT
V <sub>CC</sub>	Supply voltage		4.5	5.0	5.5	V
V <sub>IH</sub>	High-level input voltage		2.0			V
V <sub>IL</sub>	Low-level input voltage				0.8	V
l <sub>lk</sub>	Input clamp current				-18	mA
I <sub>ОН</sub>	High-level output current				-1	mA
I <sub>OL</sub>	Low-level output current				20	mA
T <sub>amb</sub>	Operating free air temperature range	Commercial range	0		+70	°C
amb	Operating nee an temperature range	Industrial range	-40		+85	°C

74F74

# DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

			TEAT AGNIDITI	0101			LIMITS		
SYMBOL	PARAMET	ER	TEST CONDITI	UN5'		MIN	TYP <sup>2</sup>	MAX	
M	High-level output voltage				$\pm 10\% V_{CC}$	2.5			V
V <sub>OH</sub>	High-level output vo	nage	$V_{CC} = MIN, V_{IL} = MAX, V_{IH} = MIN$	I <sub>OH</sub> = MAX	±5%V <sub>CC</sub>	2.7	3.4		V
M	Low-level output voltage				$\pm 10\% V_{CC}$		0.30	0.50	V
V <sub>OL</sub>			$V_{CC} = MIN, V_{IL} = MAX, V_{IH} = MIN$	I <sub>OL</sub> = MAX	±5%V <sub>CC</sub>		0.30	0.50	V
V <sub>IK</sub>	Input clamp voltage		$V_{CC} = MIN, I_I = I_{IK}$		-0.73	-1.2	V		
II.	Input current at max voltage	kimum input	$V_{CC} = MAX, V_I = 7.0V$			100	μA		
I <sub>IH</sub>	High-level input cur	rent	$V_{CC} = MAX, V_I = 2.7V$			20	μΑ		
	Low-level input	Dn, CPn	$V_{CC} = MAX, V_I = 0.5V$			-0.6	mA		
ΙL	current SDn, RDn		$V_{CC} = MAX, V_I = 0.5V$			-1.8	mA		
I <sub>OS</sub>	Short-circuit output current <sup>3</sup>		$V_{CC} = MAX$	-60		-150	mA		
I <sub>CC</sub>	Supply current (total) <sup>4</sup>		V <sub>CC</sub> = MAX		11.5	16	mA		

#### NOTES:

For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type. 1

2

All typical values are at  $V_{CC} = 5V$ ,  $T_{amb} = 25^{\circ}C$ . Not more than one output should be shorted at a time. For testing  $I_{OS}$ , the use of high-speed test apparatus and/or sample-and-hold 3 techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I<sub>OS</sub> tests should be performed last.

Measure I<sub>CC</sub> with the clock input grounded and all outputs open, then with Q and  $\overline{Q}$  outputs high in turn. 4

# **AC ELECTRICAL CHARACTERISTICS**

				LIMITS								
SYMBOL	PARAMETER	TEST CONDITION		<sub>CC</sub> = +5.0 <sub>nb</sub> = +25 0pF, R <sub>L</sub> :		$T_{amb} = 0^{\circ}C$	0V ± 10% C to +70°C R <sub>L</sub> = 500Ω	V <sub>CC</sub> = +5. T <sub>amb</sub> = -40° C <sub>L</sub> = 50pF,		UNIT		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX			
f <sub>max</sub>	Maximum clock frequency	Waveform 1	100	125		100		90		MHz		
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay CPn to Qn or Qn	Waveform 1	3.8 4.4	5.3 6.2	6.8 8.0	3.8 4.4	7.8 9.2	3.8 4.4	8.5 9.2	ns		
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay SDn, RDn_to Qn or Qn	Waveform 2	3.2 3.5	4.6 7.0	6.1 9.0	3.2 3.5	7.1 10.5	3.2 2.5	7.5 10.5	ns		

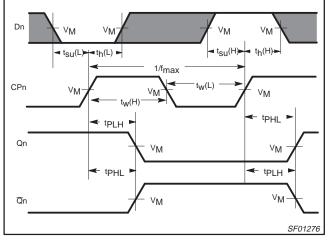
# **AC SETUP REQUIREMENTS**

			LIMITS							
SYMBOL	PARAMETER	TEST CONDITION	T <sub>ar</sub>	<sub>cc</sub> = +5.0 <sub>mb</sub> = +25 0pF, R <sub>L</sub> :	°C	$T_{amb} = 0^{\circ}C$	0V ± 10% C to +70°C R <sub>L</sub> = 500Ω	V <sub>CC</sub> = +5. T <sub>amb</sub> = -40° C <sub>L</sub> = 50pF,	0V ± 10% °C to +85°C R <sub>L</sub> = 500Ω	UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>su</sub> (H) t <sub>su</sub> (L)	Setup time, high or low Dn to CPn	Waveform 1	2.0 3.0			2.0 3.0		2.0 3.0		ns
t <sub>h</sub> (H) t <sub>h</sub> (L)	Hold time, high or low Dn to CPn	Waveform 1	1.0 1.0			1.0 1.0		1.0 1.0		ns
t <sub>w</sub> (H) t <sub>w</sub> (L)	CPn pulse width, high or low	Waveform 1	4.0 5.0			4.0 5.0		4.0 5.0		ns
t <sub>w</sub> (L)	SDn, RDn pulse width, low	Waveform 2	4.0			4.0		4.0		ns
t <sub>rec</sub>	Recovery time SDn, RDn to CPn	Waveform 3	2.0			2.0		2.0		ns

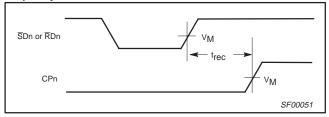
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#### AC WAVEFORMS

For all waveforms,  $V_{\rm M}$  = 1.5V. The shaded areas indicate when the input is permitted to change for predictable output performance.

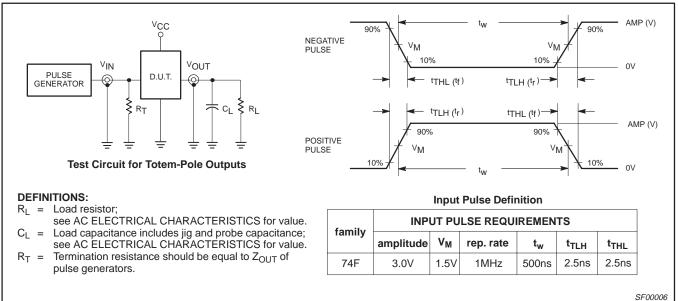


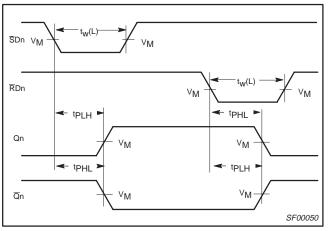
Waveform 1. Propagation delay for data to output, data setup time and hold times, and clock width, and maximum clock frequency

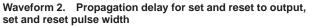


Waveform 3. Recovery time for set or reset to clock

#### **TEST CIRCUIT AND WAVEFORMS**

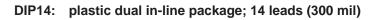


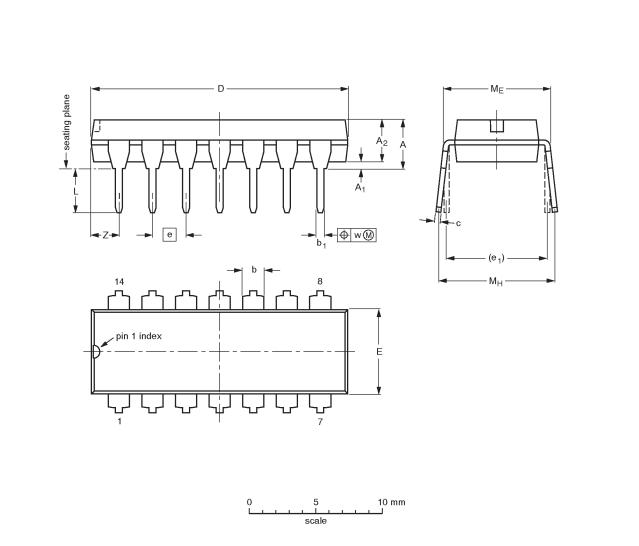




#### Product specification

SOT27-1





#### DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	e <sub>1</sub>	L	M <sub>E</sub>	M <sub>H</sub>	w	Z <sup>(1)</sup> max.
mm	4.2	0.51	3.2	1.73 1.13	0.53 0.38	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.2
inches	0.17	0.020	0.13	0.068 0.044	0.021 0.015	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.087

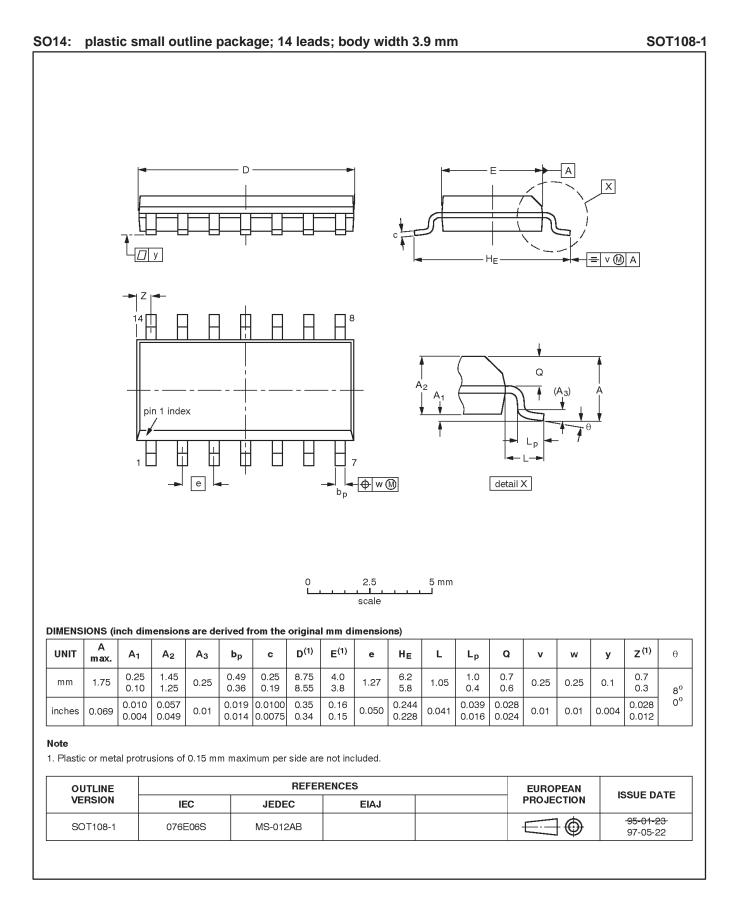
#### Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT27-1	050G04	MO-001AA			<del>-92-11-17</del> 95-03-11

Product specification

74F74



#### 1996 Mar 12

#### Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

[1] Please consult the most recently issued datasheet before initiating or completing a design.

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Limiting values definition - Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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**Philips Semiconductors** 811 East Arques Avenue P.O. Box 3409 Sunnyvale, California 94088-3409 Telephone 800-234-7381

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